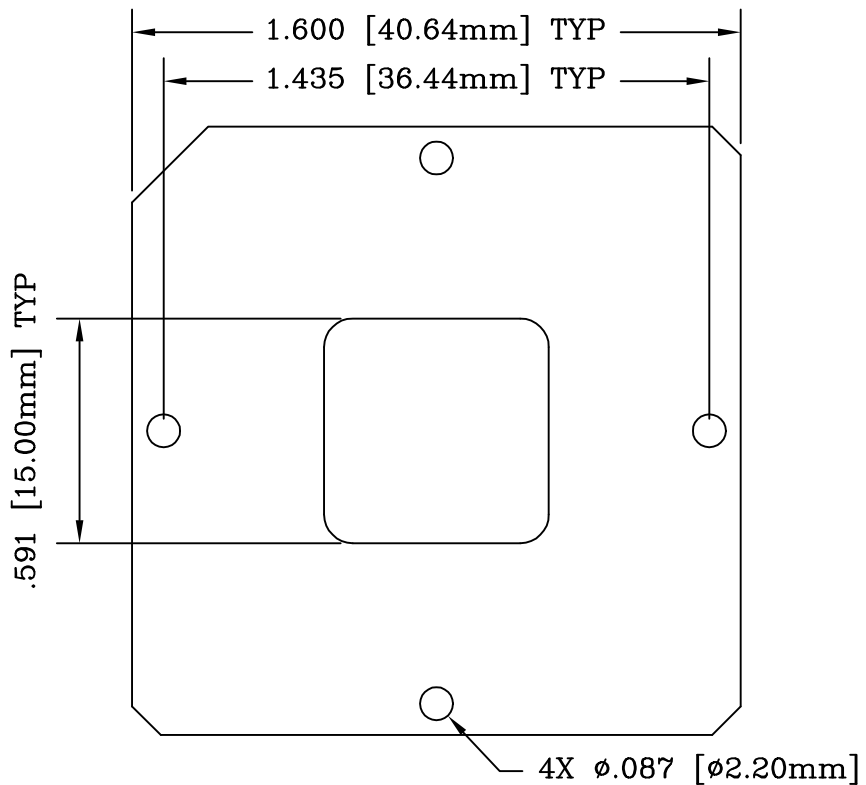
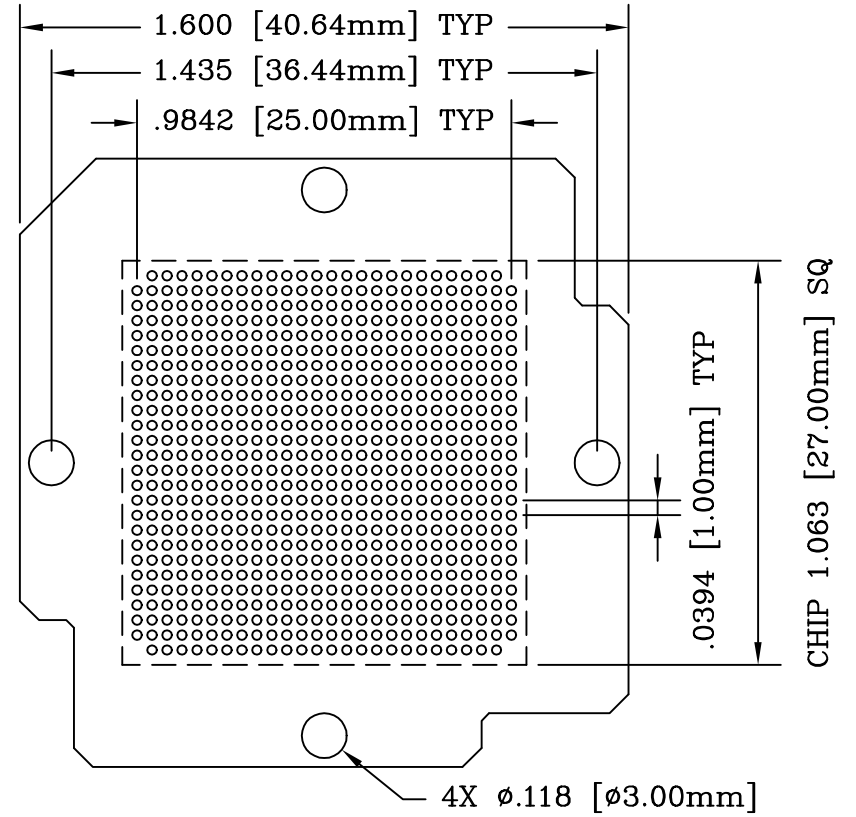


REV	DESCRIPTION	DATE	BY
A	NEW DRAWING	12/06/00	H.N.
B	ADD PACKAGE SPECIFICATIONS	03/13/01	H.N.
C	UPDATED DIM. & REC. PAD LAYOUT	02/14/03	H.N.

SKT1129
DOD 41129



RETENTION FRAME



SOCKET

RECOMMENDED PAD LAYOUT

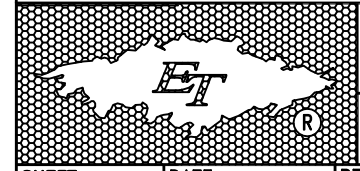
SOLDERTAIL STYLE		SOLDERTAIL = THRU HOLE STYLE	
REGULAR SMT STYLE XX = (-SM) YY = (-30)	RAISED SMT STYLE XX = (-RC) YY = (-29)	XX = (-ET) YY = (-70)	
$\phi .0236$ [Ø0.60mm]		$\phi .0197$ [Ø0.50mm]	.110 [2.80mm]
-30(SM) = .0197 [0.50mm] TO .0276 [0.70mm] -29(RC) = .0197 [0.50mm] TO .0276 [0.70mm]			
BALL DIAMETER FOR: -30(SM) = .0197 [0.50mm] TO .0276 [0.70mm] -29(RC) = .0197 [0.50mm] TO .0276 [0.70mm]		PIN DIAMETER FOR: -70(ET) = .0114 [0.29mm]	
BALL HEIGHT FOR: -30(SM) = .0118 [0.30mm] TO .0197 [0.50mm] -29(RC) = .0118 [0.30mm] TO .0197 [0.50mm]			

* All Dimensions Are Nominal For A .0394 [1.00mm] Pitch BGA Package

PACKAGE SPECIFICATIONS

PIN COUNT	= 672
LEAD PITCH	= 1.00mm
GRID SIZE	= 26X26
PACKAGE SIZE	= 27.00mm

ALL DIMENSIONS ARE IN INCHES UNLESS OTHERWISE SPECIFIED



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FAX:(408)982-0664

SHEET: 1 OF 1	DATE: 02/14/03	REVISION: C	ASSEMBLY DRAWING
CHECKED: Perry Munroe	DRAWN: Hanh Nguyen	ITEM: S-MBG-26-672-XX	
Scale 2:1	DO NOT SCALE DRAWING	DESCRIPTION: BPW-672-3BG026-YY	